



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料:PA66(UL-94V-0)
2. 接触件:黄铜镀锡
3. 接触电阻:≤10mΩ
4. 绝缘电阻:≥100MΩ
5. 额定电压:250V AC DC
6. 额定电流:2.0A AC DC
7. 耐压:能承受1000V AC/Minute
8. 工作温度:-25°~+85°
9. 可焊性试验:浸锡面积≥95%温度235±5°, 时间2.5±0.5秒
10. 铅和镉等六大有害物质含量要符合环保要求。

Part No	Pin	A	B
WAFER-PH2.0-2PZZ-GR	2	2.00	6.00
WAFER-PH2.0-3PZZ-GR	3	4.00	8.00
WAFER-PH2.0-4PZZ-GR	4	6.00	10.00
WAFER-PH2.0-5PZZ-GR	5	8.00	12.00
WAFER-PH2.0-6PZZ-GR	6	10.00	14.00
WAFER-PH2.0-7PZZ-GR	7	12.00	16.00
WAFER-PH2.0-8PZZ-GR	8	14.00	18.00
WAFER-PH2.0-9PZZ-GR	9	16.00	20.00
WAFER-PH2.0-10PZZ-GR	10	18.00	22.00
WAFER-PH2.0-11PZZ-GR	11	20.00	24.00
WAFER-PH2.0-12PZZ-GR	12	22.00	26.00
WAFER-PH2.0-13PZZ-GR	13	24.00	28.00
WAFER-PH2.0-14PZZ-GR	14	26.00	30.00
WAFER-PH2.0-15PZZ-GR	15	28.00	32.00
WAFER-PH2.0-16PZZ-GR	16	30.00	34.00
WAFER-PH2.0-17PZZ-GR	17	32.00	36.00
WAFER-PH2.0-18PZZ-GR	18	34.00	38.00
WAFER-PH2.0-19PZZ-GR	19	36.00	40.00
WAFER-PH2.0-20PZZ-GR	20	38.00	42.00

2	端子Contact	黄铜	N*1	电镀(锡):整个表面镀底镍 30u"MIN,再镀锡80u"MIN
1	基座Wafer	PA66(UL94 V-0)	1	红色

序号	名称	材料	数量	备注
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MANUFACTURE DWG  东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co.,Ltd

UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: WAFER PH2.0MM 直针	
			PAR	WAFER-PH2.0-NPZZ-GR
			DWN	
			CHKD	
DECIMALS:	ANGLES:			
.X±0.20	±2'			
.XX±0.10				
.XXX±0.05				
		CUSTOMER COPY	SCALE:1:1	UNIT:MM
			SIZE:A4	SHEET:1F1
				REV:A